Filename: BOM-PMP8913 REVB.xls

Variant: 001

Generated: 3/12/2013 8:16:27 AM **PMP8913 REVB BOM**

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C10	1	0.068uF	CAP, CERM, 0.068uF, 50V, +/-10%, X7R, 0603	0603	Std	MuRata
C12	1	0.1uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	Std	TDK
C1, C14	2	1uF	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	0603	Std	TDK
C2, C13	2	270pF	CAP, CERM, 270pF, 50V, +/-5%, C0G/NP0, 0603	0603	Std	TDK
C11	1	33pF	CAP, CERM, 33pF, 50V, +/-5%, C0G/NP0, 0603	0603	Std	TDK
C3	1	0.33uF	CAP, CERM, 0.33uF, 50V, +/-10%, X7R, 0805	0805	Std	TDK
C7	1	0.1uF	CAP, CERM, 0.1uF, 250V, +/-10%, X7R, 1206	1206	Std	TDK
C8, C9	2	10uF	CAP, CERM, 10uF, 35V, +/-10%, X7R, 1210	1210	GRM32ER7YA106KA12L	MuRata
C4, C5, C6	3	100uF	CAP, AL, 10uF, 125V, +/-20%, 0.35 ohm, SMD	SMT Radial G	EEE-FK1J101P	Panasonic
D1	1	MBRS3200T3G	Diode, Schottky, 200V, 3A, SMB	SMB	MBRS3200T3G	ON Semi
D2	1	16V	Diode, Zener, 16V, 500mW, SOD-123	SOD-123	MMSZ5246B-7-F	Diodes Inc.
D3	1	7.5V	Diode, Zener, 7.5V, 500mW, SOD-123	SOD-123	MMSZ5236B-7-F	Diodes Inc.
J1, J2	2	ED555/2DS	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25 inch	ED555/2DS	OST
L1	1	6.8uH	Inductor, Shielded E Core, Ferrite, 6.8uH, 27.8A, 0.0015 ohm, SMD	SER29xx	SER2915L-682KL	Coilcraft
Q2, Q4	2	IPB600N25N3 G	MOSFET, N-CH, 250V, 25A, DDPAK	DDPAK	IPB600N25N3 G	Infineon
Q5	1	MMBT3904-7-F	Transistor, NPN, 40V, 0.2A, SOT-23	SOT-23	MMBT3904-7-F	Diodes Inc.
Q6	1	2N7002ET1G	MOSFET, N-CH, 60V, 0.26A, SOT-23	SOT-23	2N7002ET1G	ON Semi
R1, R6	2	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	Std	Vishay-Dale
R2, R5	2	10.0	RES, 10.0 ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R14	1	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R3	1	1.00k	RES, 1.00k ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R11	1	1.00Meg	RES, 1.00Meg ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R15	1	1.40k	RES, 1.43k ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R8, R12, R16, R18	4	10.0k	RES, 10.0k ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R7	1	102k	RES, 113k ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R10	1	200k	RES, 200k ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R9	1	30.1k	RES, 30.1k ohm, 1%, 0.1W, 0603	0603	Std	Vishay-Dale
R13	1	200k	RES, 200k ohm, 1%, 0.125W, 0805	0805	Std	Vishay-Dale
R4	1	0.02	RES, 0.02 ohm, 1%, 1W, 1206	1206	Std	Susumu Co
R17	1	open	RES, open, 5%, 0.1W, 0603	0603	Std	Vishay-Dale

TP1, TP2, 6 TP5, TP6, TP7, TP8	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
' '					reysione
TP7, TP8					
TP3, TP4, 3	Black	Test Point, TH, Miniature, Black	Keystone5001	5001	Keystone
TP9					
U1 1	TPS40210DGQ	4.5 to 52 V Input Current Mode Boost Controller, 95 %	DGQ0010D	TPS40210DGQ	TI
		Duty Cycle, -40 to +125 degC, 10-pin MSOP-			
		PowerPAD (DGQ), Green (RoHS & no Sb/Br)			
U2 1	UCC27324DGN	IC, 4A High Speed Low-Side MOSFET Driver	HTSSOP	UCC27324DGN	TI

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